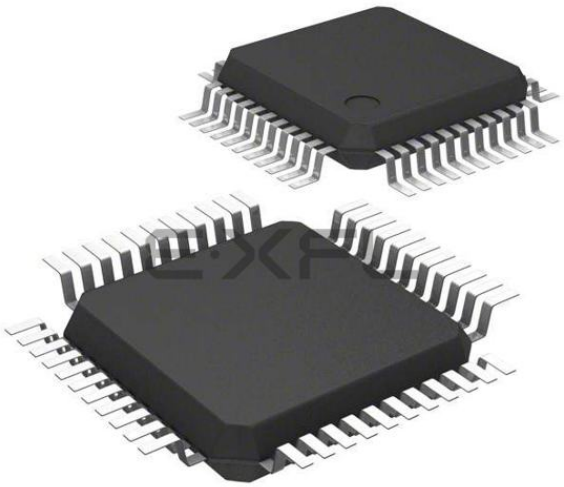
Renesas Electronics America Inc - R5F11EF8AFP#50 Datasheet



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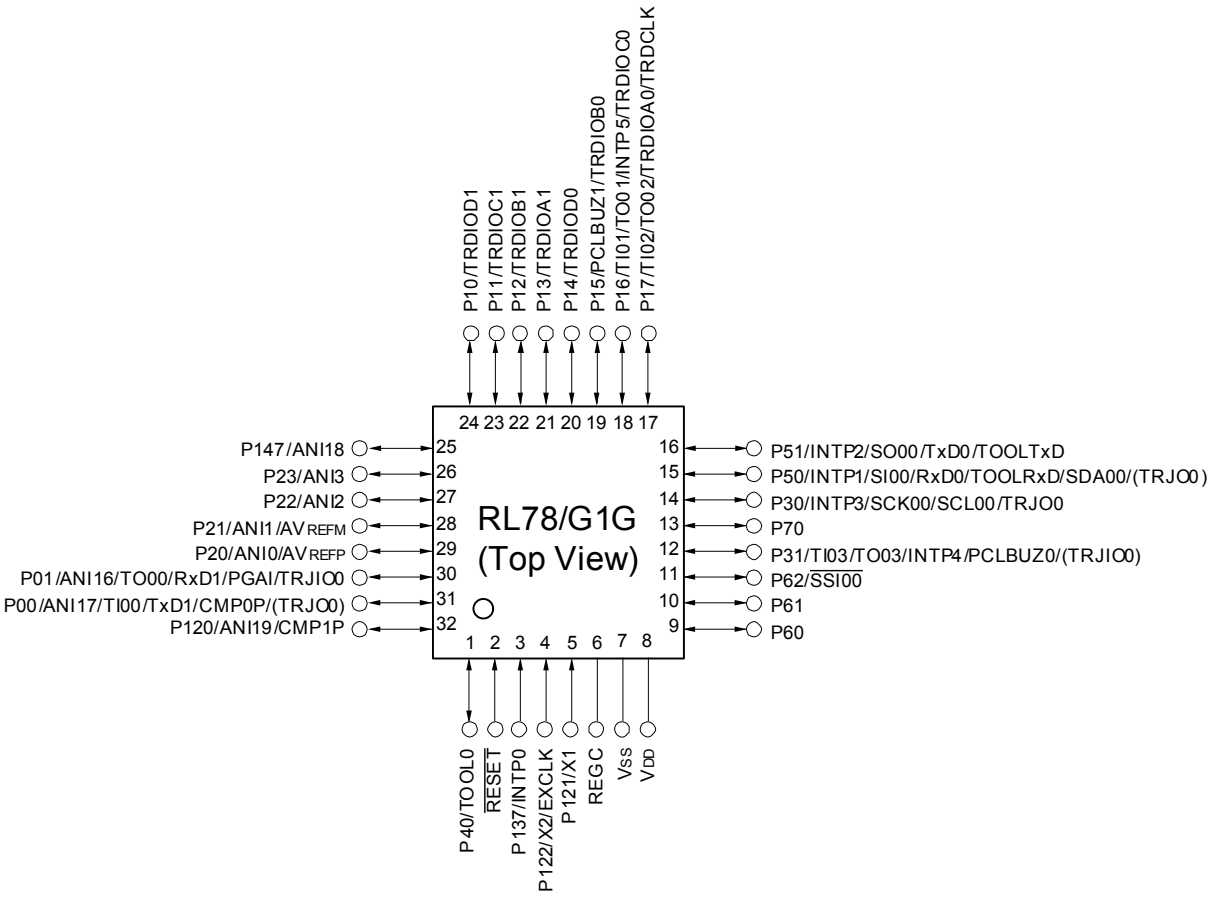
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RL78
Core Size	16-Bit
Speed	24MHz
Connectivity	CSI, I²C, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f11ef8afp-50

1.3.2 32-pin products

<R> • 32-pin plastic LQFP (7 × 7 mm, 0.8 mm pitch)



Caution Connect the REGC pin to Vss pin via a capacitor (0.47 to 1 μF).

Remark 1. For pin identification, see **1.4 Pin Identification**.

Remark 2. The functions in parentheses shown in the above figure can be assigned by setting peripheral I/O redirection register 1 (PIOR1).

1.4 Pin Identification

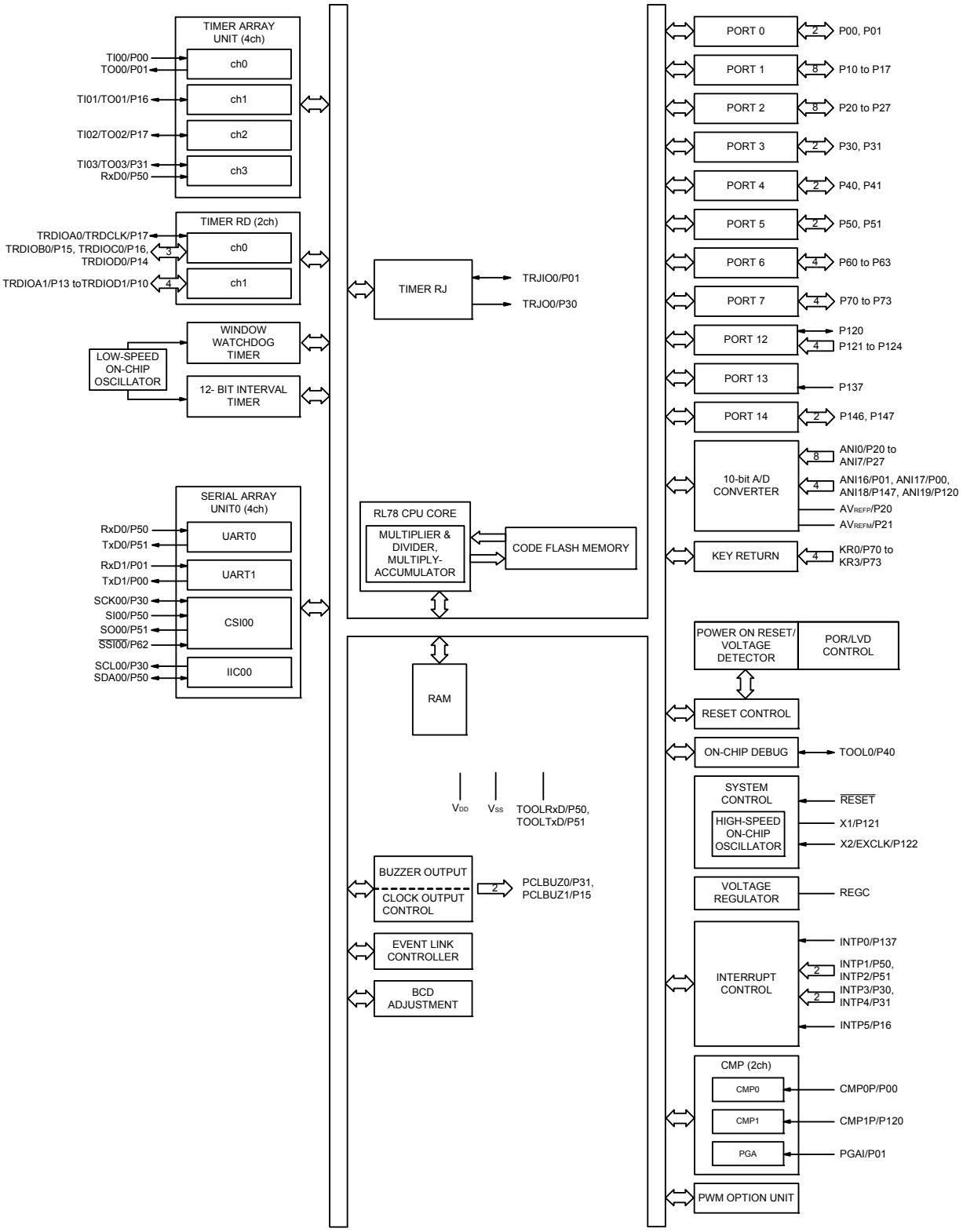
ANI0 to ANI7, ANI16 to ANI19:Analog input

AV_{REFM}:	A/D converter reference potential (- side) input
AV_{REFP}:	A/D converter reference potential (+ side) input
EXCLK:	External clock input (main system clock)
INTP0 to INTP5:	External interrupt input
KR0 to KR3:	Key Return
P00, P01:	Port 0
P10 to P17:	Port 1
P20 to P27:	Port 2
P30, P31:	Port 3
P40, P41:	Port 4
P50, P51:	Port 5
P60 to P63:	Port 6
P70 to P73:	Port 7
P120 to P124:	Port 12
P137:	Port 13
P146, P147:	Port 14
PCLBUZ0, PCLBUZ1:	Programmable clock output/buzzer output
REGC:	Regulator capacitance
$\overline{\text{RESET}}$:	Reset
RxD0, RxD1:	Receive data
SCK00:	Serial clock input/output
SCL00:	Serial clock output
SDA00:	Serial data input/output
SI00:	Serial data input
SO00:	Serial data output
$\overline{\text{SSI00}}$:	Serial interface chip select input
TI00 to TI03:	Timer input
TO00 to TO03, TRJO0:	Timer output
TOOL0:	Data input/output for tool
TOOLRxD, TOOLTxD:	Data input/output for external device
TRDCLK:	Timer external input clock

TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0,:Timer input/output
TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1,
TRJIO0

TxD0, TxD1:	Transmit data
CMP0P, CMP1P:	Comparator input
PGAI:	PGA input
V_{DD}:	Power supply
V_{SS}:	Ground
X1, X2:	Crystal oscillator (main system clock)

1.5.3 44-pin products



1.6 Outline of Functions

[30-pin, 32-pin, 44-pin products (code flash memory 8 KB to 16 KB)]

Caution The above outline of the functions applies when peripheral I/O redirection register 1 (PIOR1) is set to 00H.

(1/2)

Item		30-pin	32-pin	44-pin
		R5F11EA8ASP, R5F11EAAASP	R5F11EB8AFP, R5F11EBAAFP	R5F11EF8AFP, R5F11EFAAFP
Code flash memory (KB)		8 to 16		
RAM (KB)		1.5		
Address space		1 MB		
Main system clock	High-speed system clock	X1 (crystal/ceramic) oscillation, external main system clock input (EXCLK) LS (low-speed main) mode: 1 to 8 MHz (V_{DD} = 2.7 to 5.5 V), HS (high-speed main) mode: 1 to 20 MHz (V_{DD} = 2.7 to 5.5 V)		
	High-speed on-chip oscillator clock (f_{IH})	LS (low-speed main) mode: 1 to 8 MHz (V_{DD} = 2.7 to 5.5 V) HS (high-speed main) mode: 1 to 24 MHz (V_{DD} = 2.7 to 5.5 V)		
Low-speed on-chip oscillator clock		15 kHz (TYP.): V_{DD} = 2.7 to 5.5 V		
General-purpose register		8 bits × 32 registers (8 bits × 8 registers × 4 banks)		
Minimum instruction execution time		0.04167 μs (High-speed on-chip oscillator clock: f_{IH} = 24 MHz operation)		
		0.05 μs (High-speed system clock: f_{MX} = 20 MHz operation)		
Instruction set		• Data transfer (8/16 bits) • Adder and subtractor/logical operation (8/16 bits) • Multiplication (8 bits × 8 bits, 16 bits × 16 bits), Division (16 bits ÷ 16 bits, 32 bits ÷ 32 bits) • Multiplication and Accumulation (16 bits × 16 bits + 32 bits) • Rotate, barrel shift, and bit manipulation (Set, reset, test, and Boolean operation), etc.		
I/O port	Total	26	28	40
	CMOS I/O	23	25	35
	CMOS input	3	3	5
	CMOS output	—		
	N-ch open-drain I/O (6 V tolerance)	—		
Timer	16-bit timer	7 channels (TAU: 4 channels, Timer RJ: 1 channel, Timer RD: 2 channels)		
	Watchdog timer	1 channel		
	12-bit interval timer	1 channel		
	Timer output	Timer outputs: 14 channels PWM outputs: 9 channels		

Caution Since a library is used when rewriting the flash memory using the user program, flash ROM and RAM areas are used. Refer to the RL78 Family Flash Self-Programming Library Type01 User's Manual before using these products.

2.3 Oscillator Characteristics

2.3.1 X1 oscillator characteristics

(T_A = -40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Resonator	Conditions	MIN.	TYP.	MAX.	Unit
X1 clock oscillation frequency (f_X) Note	Ceramic resonator/ crystal resonator	2.7 V ≤ V_{DD} ≤ 5.5 V	1.0		20.0	MHz

Note Indicates only permissible oscillator frequency ranges. Refer to **AC Characteristics** for instruction execution time. Request evaluation by the manufacturer of the oscillator circuit mounted on a board to check the oscillator characteristics.

Caution **Since the CPU is started by the high-speed on-chip oscillator clock after a reset release, check the X1 clock oscillation stabilization time using the oscillation stabilization time counter status register (OSTC) by the user. Determine the oscillation stabilization time of the OSTC register and the oscillation stabilization time select register (OSTS) after sufficiently evaluating the oscillation stabilization time with the resonator to be used.**

Remark When using the X1 oscillator, refer to **5.4 System Clock Oscillator in the RL78/G1G User's Manual.**

2.3.2 On-chip oscillator characteristics

(T_A = -40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Oscillators	Parameters	Conditions	MIN.	TYP.	MAX.	Unit
High-speed on-chip oscillator clock frequency Notes 1, 2	f_{IH}		1		24	MHz
	f_{HOCO}		1		48	
High-speed on-chip oscillator clock frequency accuracy			-2		+2	%
Low-speed on-chip oscillator clock frequency	f_{IL}			15		kHz
Low-speed on-chip oscillator clock frequency accuracy			-15		+15	%

Note 1. High-speed on-chip oscillator frequency is selected with bits 0 to 4 of the option byte (000C2H) and bits 0 to 2 of the HOCODIV register.

Note 2. This only indicates the oscillator characteristics. Refer to **AC Characteristics** for instruction execution time.

2.4.2 Supply current characteristics

(1) Flash ROM: 16 KB of 30- pin to 44-pin products

(T_A = -40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(1/2)**

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD1}	Operating mode	HS (high-speed main) mode Notes 3, 4	f_{HOCO} = 48 MHz, f_{IH} = 24 MHz	Basic operation	V_{DD} = 5.0 V		1.8		mA
						V_{DD} = 3.0 V		1.8		
			HS (high-speed main) mode Notes 3, 4	f_{HOCO} = 48 MHz, f_{IH} = 24 MHz	Normal operation	V_{DD} = 5.0 V		3.9	6.9	mA
						V_{DD} = 3.0 V		3.9	6.9	
				f_{HOCO} = 24 MHz, f_{IH} = 24 MHz	Normal operation	V_{DD} = 5.0 V		3.7	6.3	
						V_{DD} = 3.0 V		3.7	6.3	
				f_{HOCO} = 16 MHz, f_{IH} = 16 MHz	Normal operation	V_{DD} = 5.0 V		2.8	4.6	
						V_{DD} = 3.0 V		2.8	4.6	
			LS (low-speed main) mode Notes 3, 4	f_{IH} = 8 MHz	Normal operation	V_{DD} = 3.0 V		1.2	2.0	mA
			HS (high-speed main) mode Notes 2, 4	f_{MX} = 20 MHz, V_{DD} = 5.0 V	Normal operation	Square wave input		3.1	5.3	mA
						Resonator connection		3.3	5.5	
				f_{MX} = 20 MHz, V_{DD} = 3.0 V	Normal operation	Square wave input		3.1	5.3	
						Resonator connection		3.3	5.5	
				f_{MX} = 10 MHz, V_{DD} = 5.0 V	Normal operation	Square wave input		2.0	3.1	
						Resonator connection		2.0	3.2	
				f_{MX} = 10 MHz, V_{DD} = 3.0 V	Normal operation	Square wave input		2.0	3.1	
						Resonator connection		2.0	3.2	
			LS (low-speed main) mode Notes 2, 4	f_{MX} = 8 MHz, V_{DD} = 3.0 V	Normal operation	Square wave input		1.2	1.9	mA
						Resonator connection		1.2	2.0	

Note 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, comparator, programmable gain amplifier, watchdog timer, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors.

Note 2. When high-speed on-chip oscillator is stopped.

Note 3. When high-speed system clock is stopped.

Note 4. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.
HS (high speed main) mode: V_{DD} = 2.7 V to 5.5 V@1 MHz to 24 MHz
LS (low speed main) mode: V_{DD} = 2.7 V to 5.5 V@1 MHz to 8 MHz

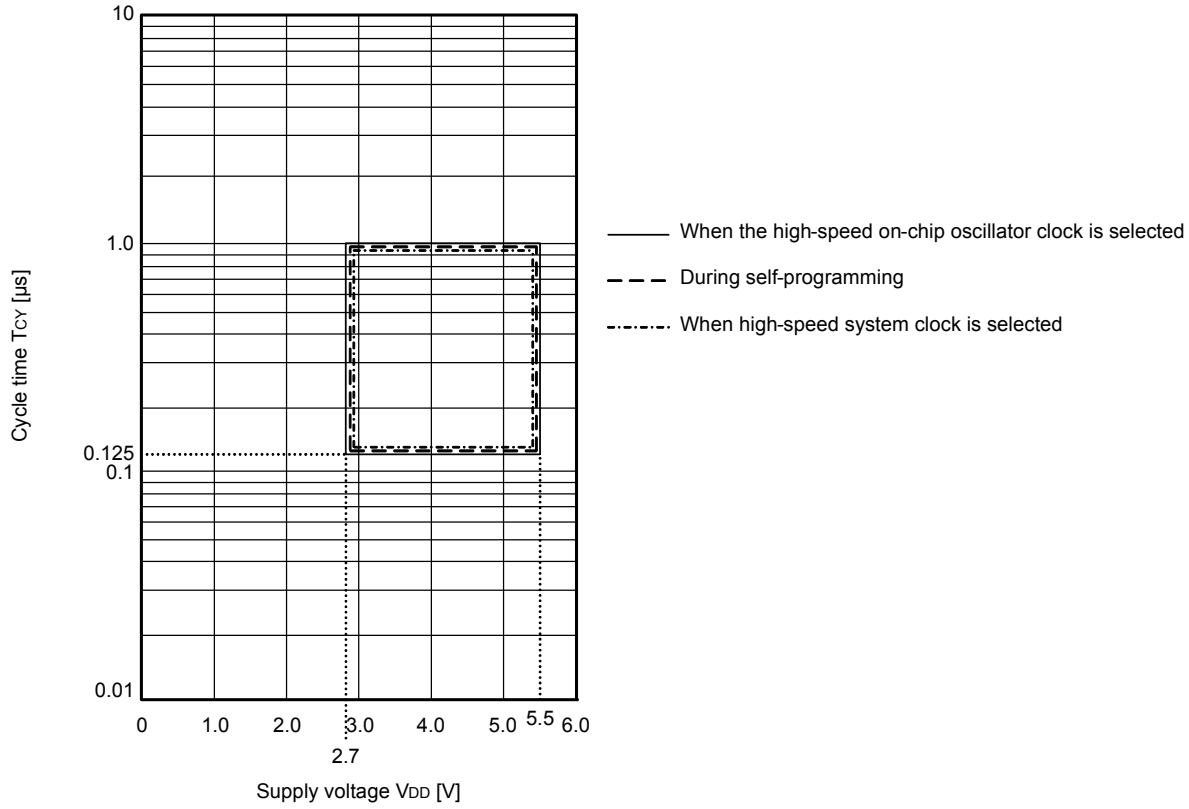
Remark 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

Remark 2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)

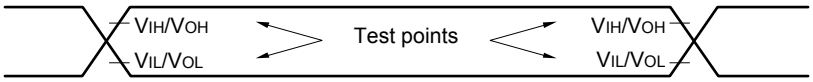
Remark 3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

Remark 4. Temperature condition of the TYP. value is T_A = 25°C

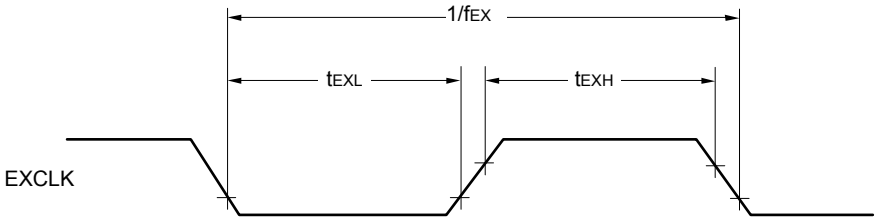
TCY vs VDD (LS (low-speed main) mode)



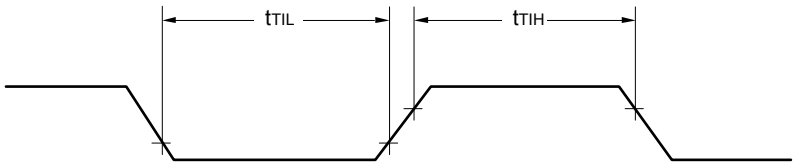
AC Timing Test Points

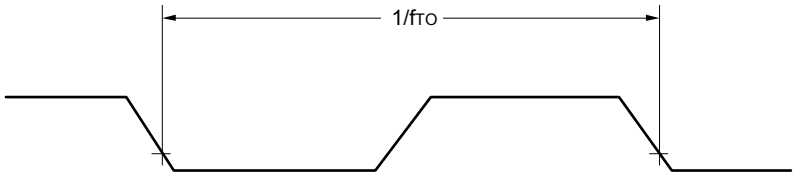


External System Clock Timing

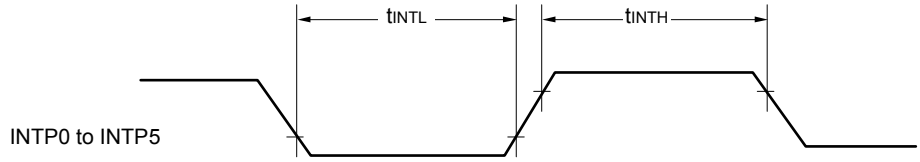


TI/TO Timing

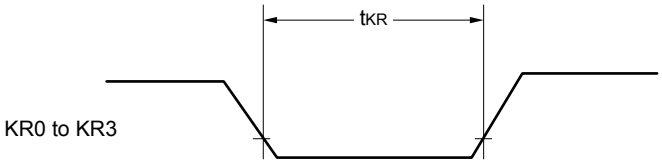




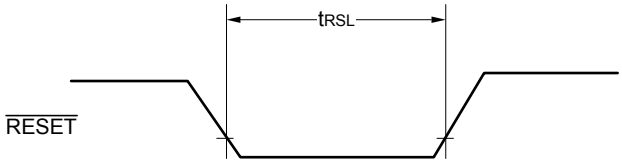
Interrupt Request Input Timing



Key Interrupt Input Timing



$\overline{\text{RESET}}$ Input Timing



(4) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input)

(T_A = -40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) mode		LS (low-speed main) mode		Unit
				MIN.	MAX.	MIN.	MAX.	
SCKp cycle time Note 5	t_{KCY2}	4.0 V ≤ V_{DD} ≤ 5.5 V	20 MHz < f_{MCK}	8/f_{MCK}		—		ns
			f_{MCK} ≤ 20 MHz	6/f_{MCK}		6/f_{MCK}		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V	16 MHz < f_{MCK}	8/f_{MCK}		—		ns
			f_{MCK} ≤ 16 MHz	6/f_{MCK}		6/f_{MCK}		ns
SCKp high-/low-level width	t_{KH2}, t_{KL2}	4.0 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2 - 7		t_{KCY2}/2 - 7		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2 - 8		t_{KCY2}/2 - 8		ns
SIp setup time (to SCKp↑) Note 1	t_{SIK2}	2.7 V ≤ V_{DD} ≤ 5.5 V		1/f_{MCK} + 20		1/f_{MCK} + 30		ns
SIp hold time (from SCKp↑) Note 2	t_{KSI2}	2.7 V ≤ V_{DD} ≤ 5.5 V		1/f_{MCK} + 31		1/f_{MCK} + 31		ns
Delay time from SCKp↓ to SOp output Note 3	t_{KSO2}	C = 30 pF Note 4	2.7 V ≤ V_{DD} ≤ 5.5 V		2/f_{MCK} + 44		2/f_{MCK} + 110	ns
$\overline{SSI00}$ setup time	t_{SSIK}	DAPmn = 0	2.7 V ≤ V_{DD} ≤ 5.5 V	120		120		ns
		DAPmn = 1	2.7 V ≤ V_{DD} ≤ 5.5 V	1/f_{MCK} + 120		1/f_{MCK} + 120		ns
$\overline{SSI00}$ hold time	t_{KSSI}	DAPmn = 0	2.7 V ≤ V_{DD} ≤ 5.5 V	1/f_{MCK} + 120		1/f_{MCK} + 120		ns
		DAPmn = 1	2.7 V ≤ V_{DD} ≤ 5.5 V	120		120		ns

Note 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes “to SCKp↓” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes “from SCKp↓” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes “from SCKp↑” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 4. C is the load capacitance of the SOp output lines.

Note 5. The maximum transfer rate when using the SNOOZE mode is 1 Mbps.

Caution Select the normal input buffer for the SIp pin and SCKp pin and the normal output mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

Remark 1. p: CSI number (p = 00), m: Unit number (m = 0), n: Channel number (n = 0), g: PIM number (g = 3, 5)

Remark 2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00))

(6) Communication at different potential (2.5 V, 3 V) (UART mode)

(T_A = -40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (1/2)

Parameter	Symbol	Conditions		HS (high-speed main) mode		LS (low-speed main) mode		Unit
				MIN.	MAX.	MIN.	MAX.	
Transfer rate		Reception	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		f_{MCK}/6 Note 1		f_{MCK}/6 Note 1	bps
			Theoretical value of the maximum transfer rate f_{MCK} = f_{CLK} Note 3		4.0		1.3	Mbps
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		f_{MCK}/6 Note 1		f_{MCK}/6 Note 1	bps
			Theoretical value of the maximum transfer rate f_{MCK} = f_{CLK} Note 3		4.0		1.3	Mbps
			2.7 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V		f_{MCK}/6 Notes 1, 2		f_{MCK}/6 Notes 1, 2	bps
			Theoretical value of the maximum transfer rate f_{MCK} = f_{CLK} Note 3		4.0		1.3	Mbps

Note 1. Transfer rate in the SNOOZE mode is 4800 bps only.
However, the SNOOZE mode cannot be used when FRQSEL4 = 1.

Note 2. Use it with V_{DD} ≥ V_b.

Note 3. The maximum operating frequencies of the CPU/peripheral hardware clock (f_{CLK}) are:
HS (high-speed main) mode: 24 MHz (2.7 V ≤ V_{DD} ≤ 5.5 V)
LS (low-speed main) mode: 8 MHz (2.7 V ≤ V_{DD} ≤ 5.5 V)

Caution Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V_{DD} tolerance) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

Remark 1. V_b[V]: Communication line voltage

Remark 2. q: UART number (q = 0, 1), g: PIM and POM number (g = 0, 5)

Remark 3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number,
n: Channel number (mn = 00 to 03)

Remark 4. V_{IH} and V_{IL} below are observation points for the AC characteristics of the serial array unit when communicating at different potentials in UART mode.
4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V: V_{IH} = 2.2 V, V_{IL} = 0.8 V
2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V: V_{IH} = 2.0 V, V_{IL} = 0.5 V
2.7 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V: V_{IH} = 1.50 V, V_{IL} = 0.32 V

(6) Communication at different potential (2.5 V, 3 V) (UART mode)

(T_A = -40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (2/2)

Parameter	Symbol	Conditions		HS (high-speed main) mode		LS (low-speed main) mode		Unit
				MIN.	MAX.	MIN.	MAX.	
Transfer rate		transmission	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		Note 1		Note 1	bps
			Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 1.4 kΩ, V_b = 2.7 V		2.8 Note 2		2.8 Note 2	Mbps
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		Note 3		Note 3	bps
			Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 2.7 kΩ, V_b = 2.3 V		1.2 Note 4		1.2 Note 4	Mbps
			2.7 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V		Note 5, 6		Note 5, 6	bps
			Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 5.5 kΩ, V_b = 1.6 V		0.43 Note 7		0.43 Note 7	Mbps

Note 1. The smaller maximum transfer rate derived by using f_{MCK}/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 4.0 V ≤ V_{DD} ≤ 5.5 V and 2.7 V ≤ V_b ≤ 4.0 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides

Note 2. This value as an example is calculated when the conditions described in the “Conditions” column are met.
Refer to **Note 1** above to calculate the maximum transfer rate under conditions of the customer.

Note 3. The smaller maximum transfer rate derived by using f_{MCK}/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 2.7 V ≤ V_{DD} < 4.0 V and 2.3 V ≤ V_b ≤ 2.7 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\} \times 3} \text{ [bps]}$$

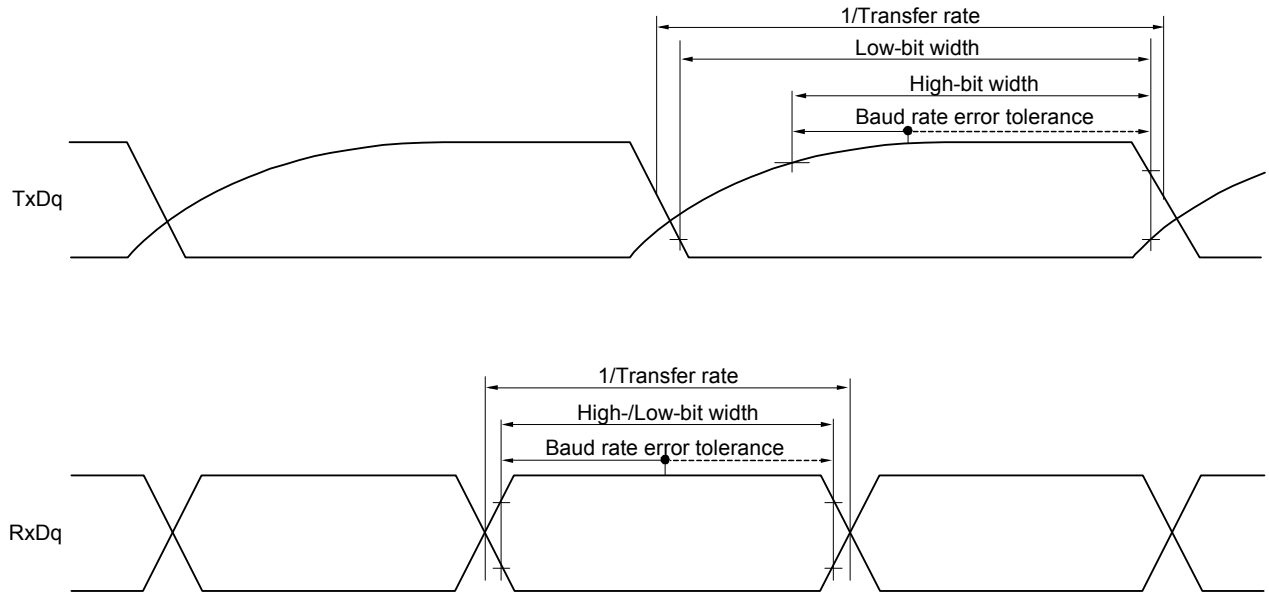
$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides

Note 4. This value as an example is calculated when the conditions described in the “Conditions” column are met.
Refer to **Note 3** above to calculate the maximum transfer rate under conditions of the customer.

Note 5. Use it with $V_{DD} \geq V_b$.

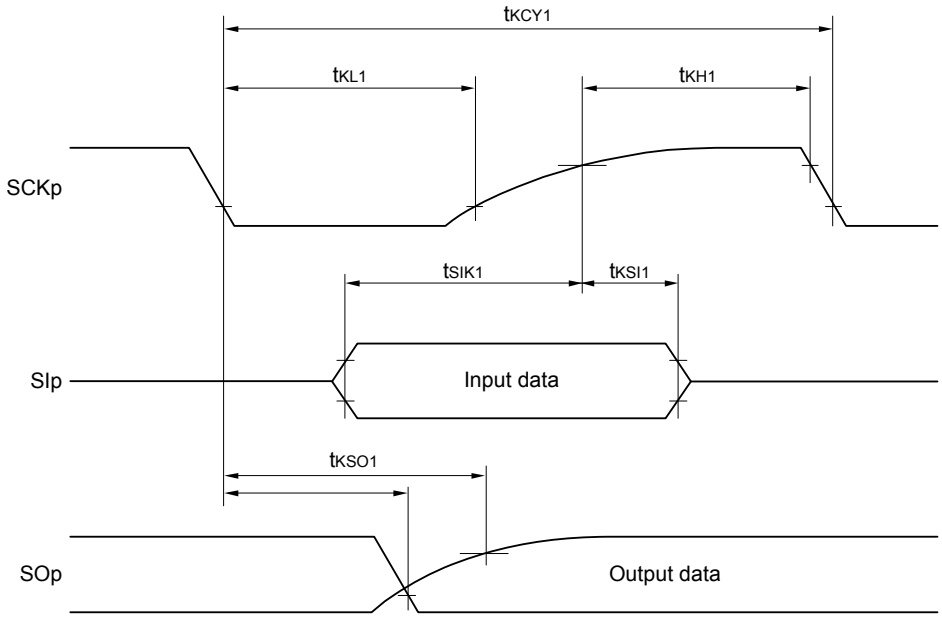
UART mode bit width (during communication at different potential) (reference)



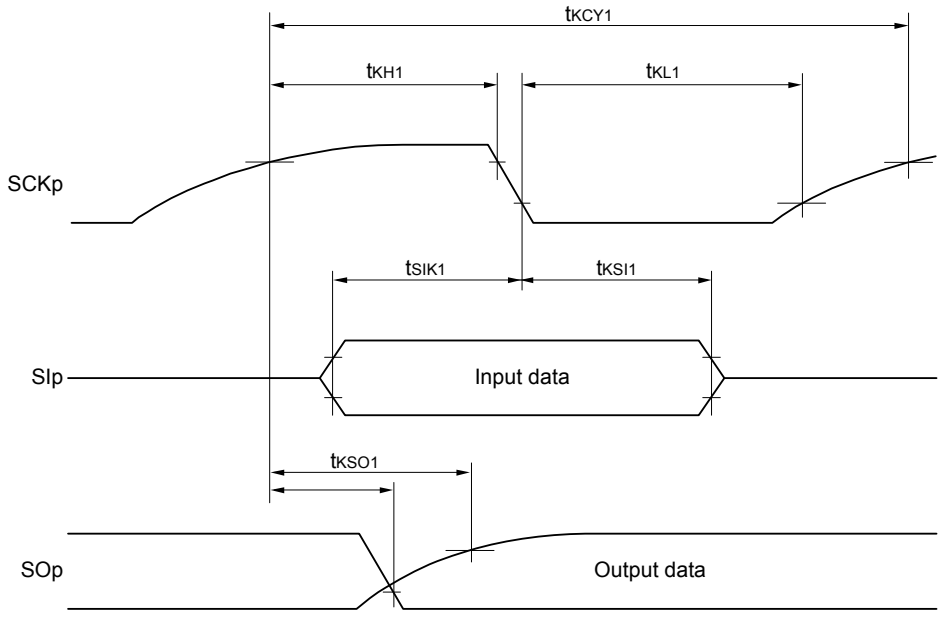
Remark 1. R_b[Ω]: Communication line (TxDq) pull-up resistance, V_b[V]: Communication line voltage

Remark 2. q: UART number (q = 0, 1), g: PIM and POM number (g = 0, 5)

CSI mode serial transfer timing (master mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)

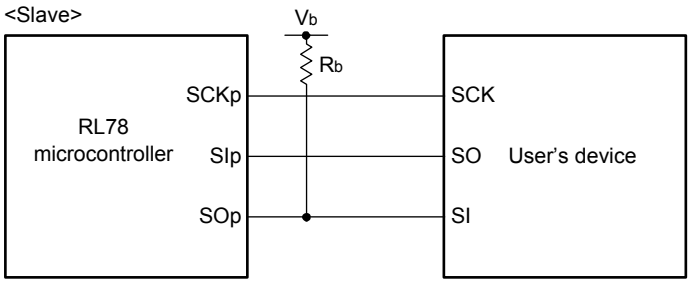


CSI mode serial transfer timing (master mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remark p: CSI number (p = 00), m: Unit number (m = 0), n: Channel number (n = 0), g: PIM and POM number (g = 3, 5)

CSI mode connection diagram (during communication at different potential)



Note 1. Transfer rate in the SNOOZE mode: MAX. 1 Mbps

Note 2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 4. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Caution Select the TTL input buffer for the SIp pin and SCKp pin, and the N-ch open drain output (V_{DD} tolerance) mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

Remark 1. R_b[Ω]: Communication line (SOp) pull-up resistance, C_b[F]: Communication line (SOp) load capacitance, V_b[V]: Communication line voltage

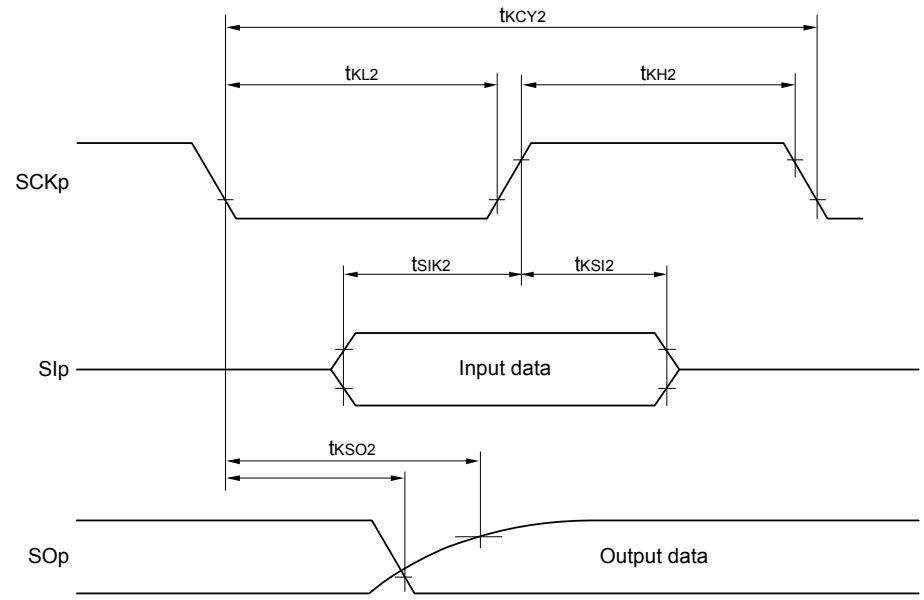
Remark 2. p: CSI number (p = 00), m: Unit number (m = 0), n: Channel number (n = 0), g: PIM and POM number (g = 3, 5)

Remark 3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn).
m: Unit number, n: Channel number (mn = 00))

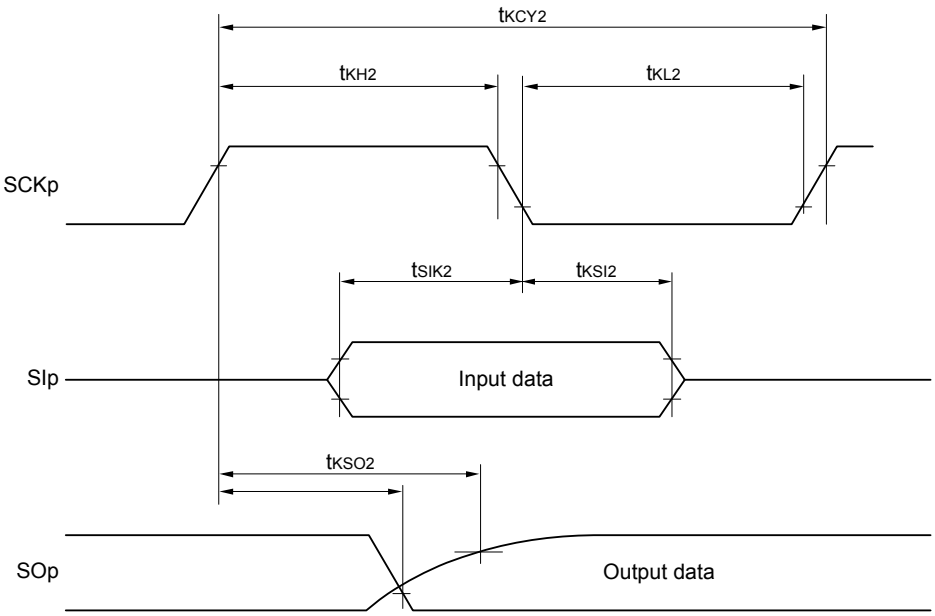
Remark 4. V_{IH} and V_{IL} below are observation points for the AC characteristics of the serial array unit when communicating at different potentials in CSI mode.
4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V: V_{IH} = 2.2 V, V_{IL} = 0.8 V
2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V: V_{IH} = 2.0 V, V_{IL} = 0.5 V

Remark 5. Communication at different potential cannot be performed during clock synchronous serial communication with the slave select function.

CSI mode serial transfer timing (slave mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



CSI mode serial transfer timing (slave mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remark 1. p: CSI number (p = 00), m: Unit number (m = 0), n: Channel number (n = 0), g: PIM and POM number (g = 3, 5)

Remark 2. Communication at different potential cannot be performed during clock synchronous serial communication with the slave select function.

2.7 Analog Characteristics

2.7.1 A/D converter characteristics

Classification of A/D converter characteristics

Input channel \ Reference Voltage	Reference voltage (+) = AVREFP Reference voltage (-) = AVREFM	Reference voltage (+) = VDD Reference voltage (-) = VSS	Reference voltage (+) = VBGR Reference voltage (-) = AVREFM
ANI0 to ANI7	Refer to **2.7.1 (1)**.	Refer to **2.7.1 (3)**.	Refer to **2.7.1 (4)**.
ANI16 to ANI19	Refer to **2.7.1 (2)**.		
Internal reference voltage Temperature sensor output voltage	Refer to **2.7.1 (1)**.		—

(1) When AVREF (+) = AVREFP/ANI0 (ADREFP1 = 0, ADREFP0 = 1), AVREF (-) = AVREFM/ANI1 (ADREFM = 1), target ANI pin: ANI2 to ANI7

(TA = -40 to +85°C, 2.7 V ≤ VDD ≤ 5.5 V, VSS = 0 V, Reference voltage (+) = AVREFP, Reference voltage (-) = AVREFM = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error Note 1	AINL	10-bit resolution AVREFP = VDD	2.7 V ≤ VDD ≤ 5.5 V		1.2	±3.5	LSB
Conversion time	tCONV	10-bit resolution AVREFP = VDD	3.6 V ≤ VDD ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ VDD ≤ 5.5 V	3.1875		39	μs
Zero-scale error Notes 1, 2	EZS	10-bit resolution AVREFP = VDD	2.7 V ≤ VDD ≤ 5.5 V			±0.25	% FSR
Full-scale error Notes 1, 2	EFS	10-bit resolution AVREFP = VDD	2.7 V ≤ VDD ≤ 5.5 V			±0.25	% FSR
Integral linearity error Note 1	ILE	10-bit resolution AVREFP = VDD	2.7 V ≤ VDD ≤ 5.5 V			±2.5	LSB
Differential linearity error Note 1	DLE	10-bit resolution AVREFP = VDD	2.7 V ≤ VDD ≤ 5.5 V			±1.5	LSB
Reference voltage (+)	AVREFP			2.7		VDD	V
Analog input voltage	VAIN			0		AVREFP	V
	VBGR	Select internal reference voltage output, 2.7 V ≤ VDD ≤ 5.5 V, HS (high-speed main) mode		1.38	1.45	1.5	V

Note 1. Excludes quantization error (±1/2 LSB).

Note 2. This value is indicated as a ratio (% FSR) to the full-scale value.

(2) When AVREF (+) = AVREFP/ANI0 (ADREFP1 = 0, ADREFP0 = 1), AVREF (-) = AVREFM/ANI1 (ADREFM = 1), target ANI pin: ANI16 to ANI19

(T_A = -40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = AVREFP, Reference voltage (-) = AVREFM = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error Note 1	AINL	10-bit resolution AVREFP = VDD	2.7 V ≤ VDD ≤ 5.5 V		1.2	±5.0	LSB
Conversion time	tCONV	10-bit resolution AVREFP = VDD	3.6 V ≤ VDD ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ VDD ≤ 5.5 V	3.1875		39	μs
Zero-scale error Notes 1, 2	EZS	10-bit resolution AVREFP = VDD	2.7 V ≤ VDD ≤ 5.5 V			±0.35	% FSR
Full-scale error Notes 1, 2	EFS	10-bit resolution AVREFP = VDD	2.7 V ≤ VDD ≤ 5.5 V			±0.35	% FSR
Integral linearity error Note 1	ILE	10-bit resolution AVREFP = VDD	2.7 V ≤ VDD ≤ 5.5 V			±3.5	LSB
Differential linearity error Note 1	DLE	10-bit resolution AVREFP = VDD	2.7 V ≤ VDD ≤ 5.5 V			±2.0	LSB
Reference voltage (+)	AVREFP			2.7		VDD	V
Analog input voltage	VAIN			0		AVREFP	V
	VBGR	Select internal reference voltage output, 2.7 V ≤ VDD ≤ 5.5 V, HS (high-speed main) mode		1.38	1.45	1.5	V

Note 1. Excludes quantization error (±1/2 LSB).

Note 2. This value is indicated as a ratio (% FSR) to the full-scale value.

(3) When AVREF (+) = VDD (ADREFP1 = 0, ADREFP0 = 0), AVREF (-) = VSS (ADREFM = 0), target ANI pin: ANI0 to ANI7, ANI16 to ANI19

(TA = -40 to +85°C, 2.7 V ≤ VDD ≤ 5.5 V, VSS = 0 V, Reference voltage (+) = VDD, Reference voltage (-) = VSS)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error Note 1	AINL	10-bit resolution	2.7 V ≤ VDD ≤ 5.5 V		1.2	±7.0	LSB
Conversion time	tCONV	10-bit resolution	3.6 V ≤ VDD ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ VDD ≤ 5.5 V	3.1875		39	μs
Zero-scale error Notes 1, 2	EZS	10-bit resolution	2.7 V ≤ VDD ≤ 5.5 V			±0.60	% FSR
Full-scale error Notes 1, 2	EFS	10-bit resolution	2.7 V ≤ VDD ≤ 5.5 V			±0.60	% FSR
Integral linearity error Note 1	ILE	10-bit resolution	2.7 V ≤ VDD ≤ 5.5 V			±4.0	LSB
Differential linearity error Note 1	DLE	10-bit resolution	2.7 V ≤ VDD ≤ 5.5 V			±2.0	LSB
Analog input voltage	VAIN	ANI0 to ANI7		0		VDD	V
		ANI16 to ANI19		0		VDD	V
	VBGR	Select internal reference voltage output, 2.7 V ≤ VDD ≤ 5.5 V, HS (high-speed main) mode		1.38	1.45	1.5	V

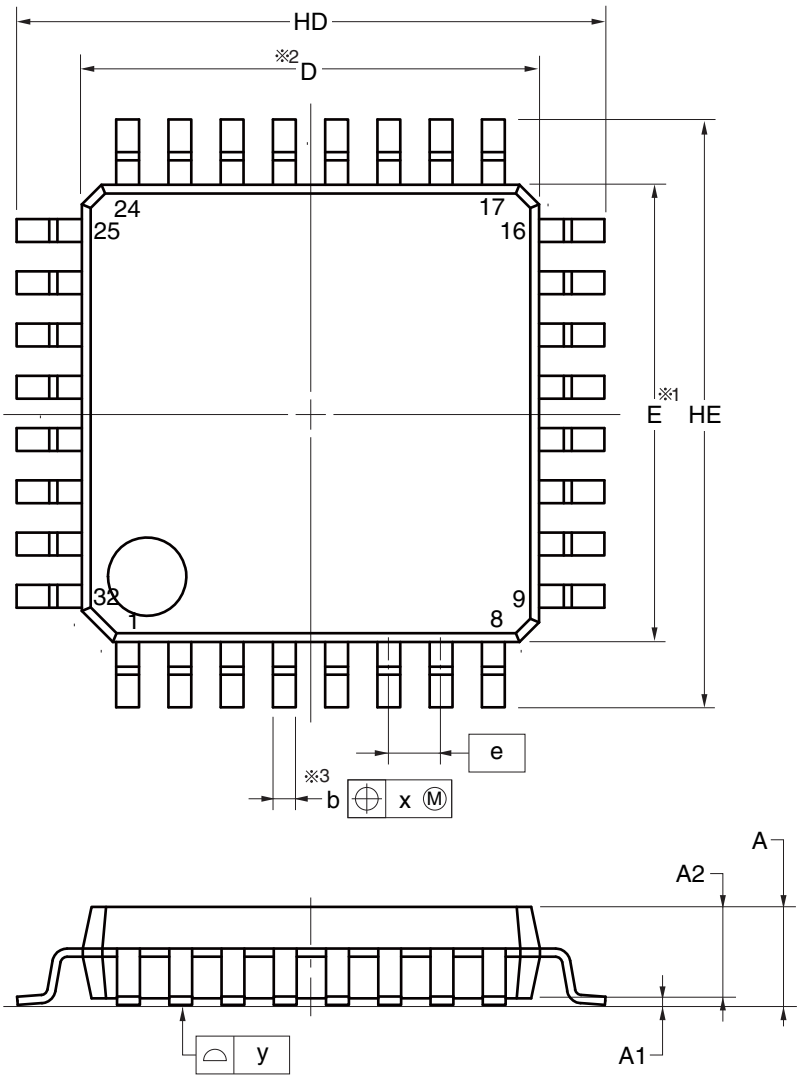
Note 1. Excludes quantization error (±1/2 LSB).

Note 2. This value is indicated as a ratio (% FSR) to the full-scale value.

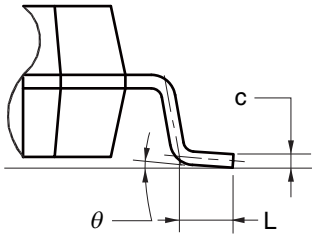
3.2 32-pin Products

R5F11EB8AFP, R5F11EBAAFP

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LQFP32-7x7-0.80	PLQP0032GB-A	P32GA-80-GBT-1	0.2



detail of lead end



(UNIT:mm)

ITEM	DIMENSIONS
D	7.00±0.10
E	7.00±0.10
HD	9.00±0.20
HE	9.00±0.20
A	1.70 MAX.
A1	0.10±0.10
A2	1.40
b	0.37±0.05
c	0.145±0.055
L	0.50±0.20
θ	0° to 8°
e	0.80
x	0.20
y	0.10

NOTE

1.Dimensions "※1" and "※2" do not include mold flash.

2.Dimension "※3" does not include trim offset.